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LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT Kidd, et al.	
		FILING DATE October 26, 1999	GROUP 1762

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	ISSUE DATE	NAME OF INVENTOR	CLASS	SUBCLASS	FILING DATE (if appropriate)
	4,062,319	Dec. 13, 1977	Roth et al.	118	49.1	Jan. 10, 1977
	5,611,655	Mar. 18, 1997	Fukasawa et al.	414	217	Jan. 4, 1996
	5,863,842	Jan. 26, 1999	Tadahiro Ohmi	438	758	May 24, 1996
	6,503,379	Jan. 7, 2003	Kidd et al.	204	298.05	May 22, 2000
	6,521,104	Feb. 18, 2003	Kidd et al.	204	298.05	May 22, 2000

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY FILED IN OR PCT	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER ART

(Include name of author (in CAPITAL LETTERS), title of article, title of item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume issue number(s), publisher, city and/or country where published)

EXAMINER INITIAL	
	U.S. Patent Application Publication No. 2003/0180450; published 9/25/03, entitled <i>System and Method for Preventing Breaker Failure</i> , Inventors: Kidd, et al.; (Attorney Docket No. 88742.472007).
	U.S. Patent Application Publication No. 2003/0136670; published 7/24/03 entitled <i>Mobile Plating System and Method</i> ; Inventors: Kidd, et al.; (Attorney Docket No. 88742.31).
	U.S. Patent Application Publication No. 2003/0121776; published 7/3/03 entitled <i>Mobile Plating System and Method</i> ; Inventors: Kidd, et al.; (Attorney Docket No. 88742.28).
	U.S. Patent Application Publication No. 2003/0159926, published 8/28/03; entitled <i>Configurable Vacuum System and Method</i> ; Inventors: Kidd, et al. (Attorney Docket No. 88742.54).

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